

Bedrock R8000 Options

Rev 2.02 | 12-Aug-2025

CPU

Select one

Ryzen 9 Pro 8945HS

45W APU 8C/16T

AI

ECC

Ryzen Embedded 8845HS

45W APU 8C/16T

10y

AI

ECC

Ryzen Embedded 8840U

15W APU 8C/16T

10y

AI

ECC

AMD Ryzen 3 7440U

15W APU 4C/8T

Enclosure should be matched to CPU power. See below **Enclosure / Walls**

CPU is soldered down on **Bedrock R7000 SoM** (System on Module)

RAM

Select one

No RAM

Requires applying thermal paste

8 GB

1x8 GB DDR5

16 GB

2x8 GB DDR5

32 GB

2x16 GB DDR5

32 GB ECC

2x16 GB DDR5 ECC

64 GB

2x32 GB DDR5

RAM is **2x SODIMM DDR5**

ECC is supported by **Pro / Embedded** CPUs only.

Main storage

Select one

No main storage

960 GB PLP

Micron 7450

PLP: power loss protection

Gen 4

1 TB

Samsung EVO 990 Pro

Gen 4

2 TB

Samsung EVO 990 Pro

Gen 4

4 TB

Samsung EVO 990 Pro

Gen 4

256 GB

ADATA 710

Gen 3

512 GB

ADATA 710

Gen 3

1 TB

ADATA 710

Gen 3

2 TB

ADATA 710

Gen 3

Additional storage devices can be installed. See below **SX / PCIe x4 slot**

OS

Select one

No OS

Ubuntu Linux

Windows 11 IOT

NIO

Select one

NIO R8000 4X25

4x 2.5 GbE, USB4

NIO R7000 Basic

2x 2.5 GbE

NIO is **Networking & I/O** board

SX

Select one

No SX

SX 4M2

4x M.2 sockets

SX is **Storage & Extension Cards** board

No extension options

PCIe x4 slot 1

Select one

No device

960 GB PLP

Micron 7450

PLP: power loss protection

Gen 4

1 TB

Samsung EVO 990 Pro

Gen 4

2 TB

Samsung EVO 990 Pro

Gen 4

4 TB

Samsung EVO 990 Pro

Gen 4

1 TB

ADATA 710

Gen 3

2 TB

ADATA 710

Gen 3

Hailo-8

AI acceleration module

PCIe x4 slot 2

Select one

No device

960 GB PLP

Micron 7450

PLP: power loss protection

Gen 4

1 TB

Samsung EVO 990 Pro

Gen 4

2 TB

Samsung EVO 990 Pro

Gen 4

4 TB

Samsung EVO 990 Pro

Gen 4

1 TB

ADATA 710

Gen 3

2 TB

ADATA 710

Gen 3

Hailo-8

AI acceleration module

M.2 key-E

Select one

No WiFi

Customer's WiFi

M.2 key-E 2230

PCIe + USB 2

Requires antennas

WiFi 6E

Intel AX210

Requires antennas

Hailo-8

AI acceleration module

For antennas, see below **Enclosure / Top panel**

Modem

Select one

No modem

Customer's modem

M.2 key-E 2230

USB 3.2

Requires antennas & SIM

LTE Cat 4

Quectel EM05-G

Requires antennas & SIM

LTE Cat 12

Quectel EM12-G

Requires antennas & SIM

5G

Quectel RM520N

Requires antennas & SIM

For antennas, see below **Enclosure / Top panel**

For SIM, see below **Enclosure / Rear panel**

PM

Select one

No PM

12V - 24V DC in

PM 1260

12V - 60V DC in

PM 1248

12V - 48V DC in

PM is **Power Module**

DCCON

Select one

DCCON

Phoenix terminal

DCCON is **DC in Connector**

Enclosure

Select one

Without enclosure

requires customer's thermal design

Enclosure

No enclosure options

Walls

Select one

Tile

29x160x130 mm

15W / 45W CPU

Conduction cooling

30W enclosure

45x160x130 mm

15W CPU

Passive cooling

60W enclosure

73x160x130 mm

45W CPU

Passive cooling

Front panel

Select one

Panel R7000 Basic

Required for NIO R7000 Basic

Panel R8000 4X25

Required for NIO R8000 4X25

Top panel

Select one

Generic top panel

No antennas

Top panel with antennas

Required for Wifi or modem

Rear panel

Select one

Generic rear panel

Rear panel with SIM trays

Required for modem

Bottom panel

Select one

Generic bottom panel

Temperature

Select one

Commercial

0°C to 70°C

Industrial

-40°C to 85°C

